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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
10/828,887	04/21/2004	Yisuo Li	CS03-028	5854
7590 04/06/2006		EXAMINER		
STEPHEN B. ACKERMAN			THOMAS, TONIAE M	
28 DAVIS AVENUE POUGHKEEPSIE, NY 12603			ART UNIT	PAPER NUMBER
			2822	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(a)				
	Application No.	Applicant(s)				
	10/828,887	LI ET AL.				
Office Action Summary	Examiner	Art Unit				
	Toniae M. Thomas	. 2822				
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	orrespondence address				
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DA - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be timused and will expire SIX (6) MONTHS from a cause the application to become ABANDONE	N. nely filed the mailing date of this communication. D (35 U.S.C. § 133).				
Status		•				
1) Responsive to communication(s) filed on 21 No.	ovember 2005.	•				
2a) This action is FINAL . 2b) This	This action is FINAL . 2b) This action is non-final.					
,	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is					
closed in accordance with the practice under E	x parte Quayle, 1935 C.D. 11, 45	53 O.G. 213.				
Disposition of Claims	•					
4) ☐ Claim(s) 1-16 is/are pending in the application. 4a) Of the above claim(s) is/are withdray 5) ☐ Claim(s) 1-16 is/are allowed. 6) ☐ Claim(s) is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or	vn from consideration.					
Application Papers						
9)⊠ The specification is objected to by the Examiner 10)⊠ The drawing(s) filed on 21 November 2005 is/an Applicant may not request that any objection to the of Replacement drawing sheet(s) including the correction 11)□ The oath or declaration is objected to by the Ex	re: a)⊠ accepted or b)⊡ object drawing(s) be held in abeyance. See ion is required if the drawing(s) is obj	e 37 CFR 1.85(a). lected to. See 37 CFR 1.121(d).				
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the prior application from the International Bureau * See the attached detailed Office action for a list of	s have been received. s have been received in Applicati ity documents have been receive (PCT Rule 17.2(a)).	on No ed in this National Stage				
Attaches with						
Attachment(s) 1) Notice of References Cited (PTO-892)	4) Interview Summary	(PTO 413)				
2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date	Paper No(s)/Mail Da					

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DETAILED ACTION

This Office action is responsive to the amendment filed on 21 November
 2005.

2. Currently, claims 1-16 are pending.

Drawings

3. The replacement drawing sheet received on 21 November 2005 is acceptable.

Specification

4. The specification is objected to because of the following informalities: "A" should be changed to "Å" (page 1, line 14; page 5, line 12; page 5, line 13; page 5, line 15; page 6, line 12; page 7, line 5; page 7, line 10; and page 8, line 3).

Also, the subscript "t" in "V_t" is not clearly distinguishable (page 6, line; page 6, line 10; page 6, line 14; page 6, line 18; page 6, line 20; page 7, line 3; and page 7, line 4 - both occurrences). Appropriate correction is required.

Claim Objections

5. Claim 2 is objected to because of the following informalities: "25 Å 120Å" should be changed to "25 Å - 120 Å". Appropriate correction is required.

Response to Arguments

6. Applicant's arguments, see page 9, lines 10-17, filed 21 November 2005 with respect to claims 1, 9, and 13 have been fully considered and are persuasive. Therefore, the rejection of claim 1 under 35 USC 102(b) and the

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rejection of claims 9 and 13 under 35 USC 103(a), as set forth in the Office action mailed on 12 September 2005, have been withdrawn.

The amendment filed on 21 November 2005 has overcome the objection to claims 10 and 14, and the rejection of claims 1-8 under 35 USC 112, second paragraph, as set forth in the Office action mailed on 12 September 2005.

Accordingly, the objection and rejection have been withdrawn.

Allowable Subject Matter

7. Claims 1-16 are allowable over the prior art of record. It is known to form a silicon dioxide layer on a semiconductor substrate, form a silicon nitride layer on the silicon dioxide layer, form isolation trench regions in the substrate, and remove the nitride layer, as evidenced by Efland et al. (US 6,468,849 B1, see figs. 6A-6D and col. 7, line 51 - col. 9, line 3). It is also known to perform a first implantation of dopant through a silicon dioxide layer, perform a second implantation of dopant through the silicon oxide layer to form wells, and remove the silicon oxide layer, as evidenced by Cho et al. (US 2004/0033658 A1 - see fig. 2C and par. 0016, lines 1-12; fig. 2D and par. 0019, lines 1-3). However, the prior art of record does not anticipate, teach or suggest a method of forming a semiconductor device substantially as claimed, wherein the method comprises forming a silicon dioxide layer on a semiconductor substrate, forming a silicon nitride layer on the silicon dioxide layer, forming

¹ The Efland et al. reference was relied upon in the previous Office action mailed on 12 September 2005.

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isolation trench regions in the substrate, removing the nitride layer, and performing a first implantation through the silicon dioxide.

Conclusion

8. This application is in condition for allowance except for the formal matters discussed above.

Prosecution on the merits is closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.

A shortened statutory period for reply to this action is set to expire **TWO**MONTHS from the mailing date of this letter.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Toniae M. Thomas whose telephone number is (571) 272-1846. The examiner can normally be reached on Monday through Friday from 8:30 a.m. to 5:30 p.m.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Zandra Smith can be reached on (571) 272-2429. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

TMT 02 April 2006

Mary Wilczewski Primery Examiner